

# Collaboration across borders

Magnus Fredriksson Ph.D.



## Alfa Laval key figures

Founded in

1883

**Employees** 

22,000+

140 years of experience in engineering and innovation

37 major production units globally Presence in over 100 countries

Order intake 2023 (MSEK)

70 742

**Patents** 

4,200+

EBITA: 16.1 % ROCE: 21.0 % Annual investment in research and innovation: 2.5 % of total net sales

### Key technologies

Applicable in +20 different product groups



**Heat transfer** 

Separation

Fluid handling





## The world is facing some **big challenges**

These include rising demand for:





Proximity to material research is crucial for success



Green hydrogen



Carbon capture utilization and storage (CCU/S)



Fuel cells



Biofuels



Energy storage



Concentrated Solar Power (CSP)



Power-to-X



Wind power

## Large scale research infrastructures

Toolbox of excellence in our network









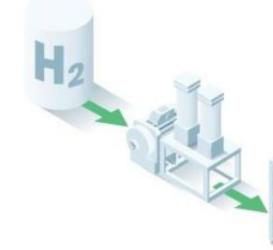






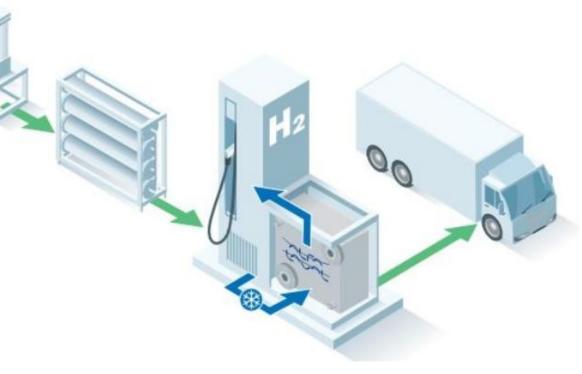






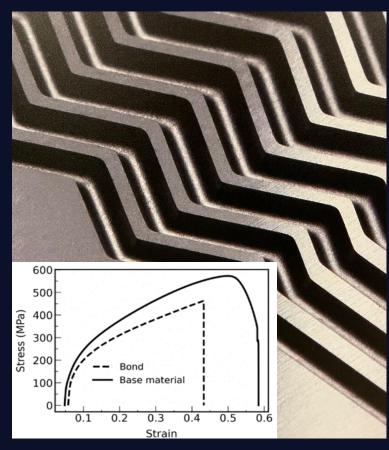


Alfa Laval HyBloc

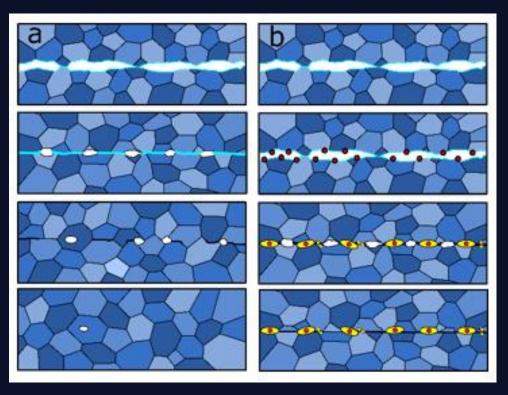








Heat transfer plate

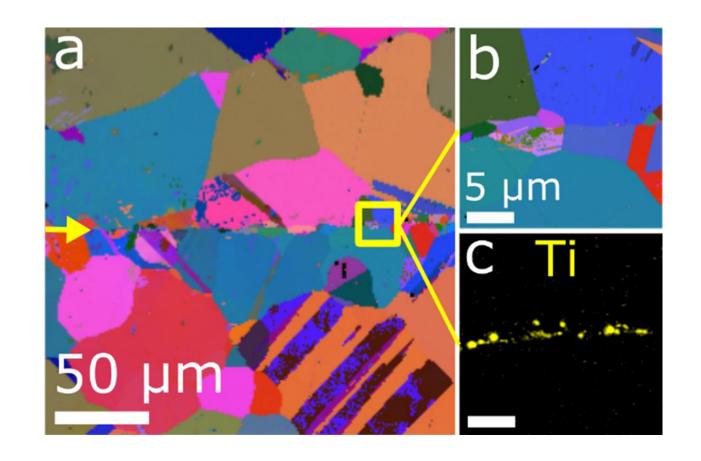


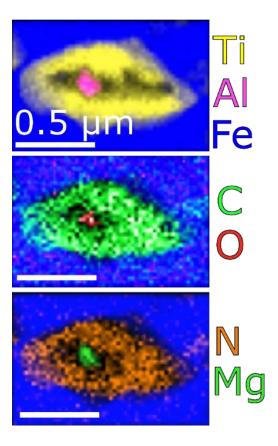
Precipitations at the bond interface prevent adequate grain migration.





EBSD and EDS of the joint cross-section

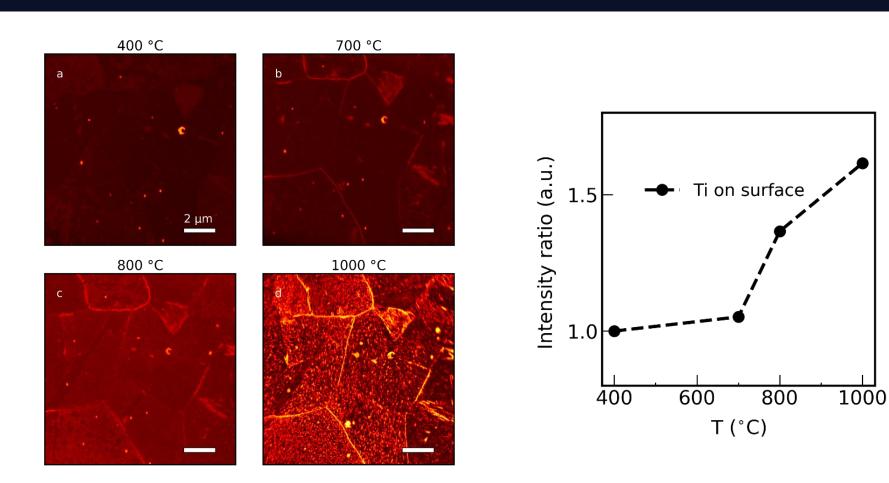






### In situ characterization using MAXPEEM

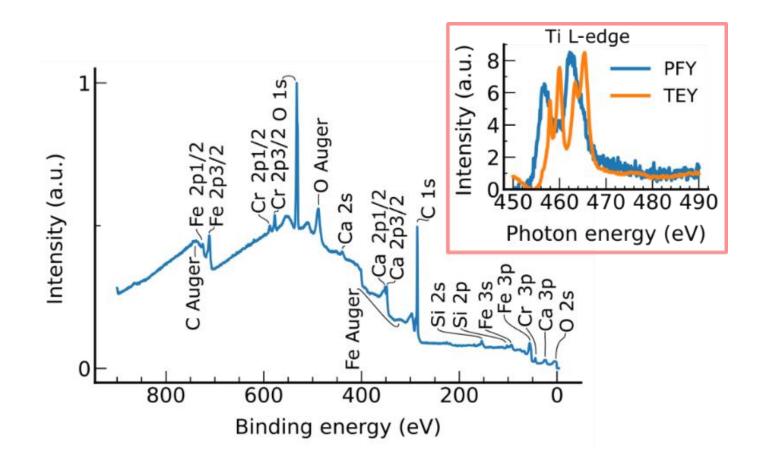
XAS-PEEM images show increase in Ti concentration and agglomeration as temperature rises





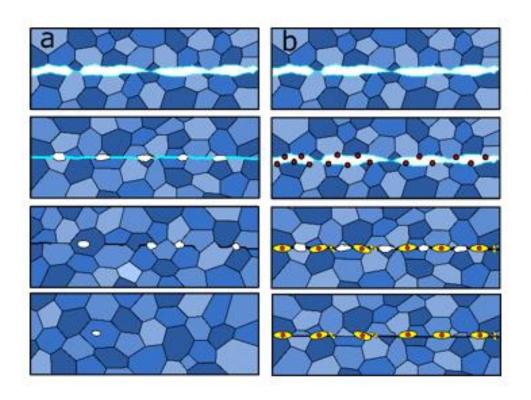
## Using FlexPES for surface analysis

X-ray photoemission spectrum of 321H steel at room temperature



### Outcome





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### Diffusion Bonding 321-Grade Stainless Steel: Failure and Multimodal Characterization

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### Abstract

Vacuum diffusion-bonded printed circuit heat exchangers are an attractive choice for the high-temperature, high-pressure demands of next-generation energy applications. However, early reports show that the high-temperature materials desired for these applications suffer from poor bond strengths due to precipitation at the bond line, preventing grain boundary migration. In this study, a diffusion bond of the high-temperature stainless steel grade 321H is investigated, and poor mechanical properties are found to be caused by Ti(C, N) precipitation at the bond line. Through *in situ* studies, it is found that Ti diffuses from the bulk to the mating surfaces at high temperatures. The Ti subsequently precipitates and, for the first time, an interaction between Ti(C, N) and Al/Mg-oxide precipitates at the bond line is observed, where Ti(C, N) nucleates on the oxides forming a core-shell structure. The results indicate that small amounts of particular alloying elements can greatly impact diffusion bond quality, prompting further research into the microstructural evolution that occurs during bonding conditions.

Key words: core-shell, diffusion bonding, microstructure, PEEM, stainless steel, TEM, Ti-rich precipitation









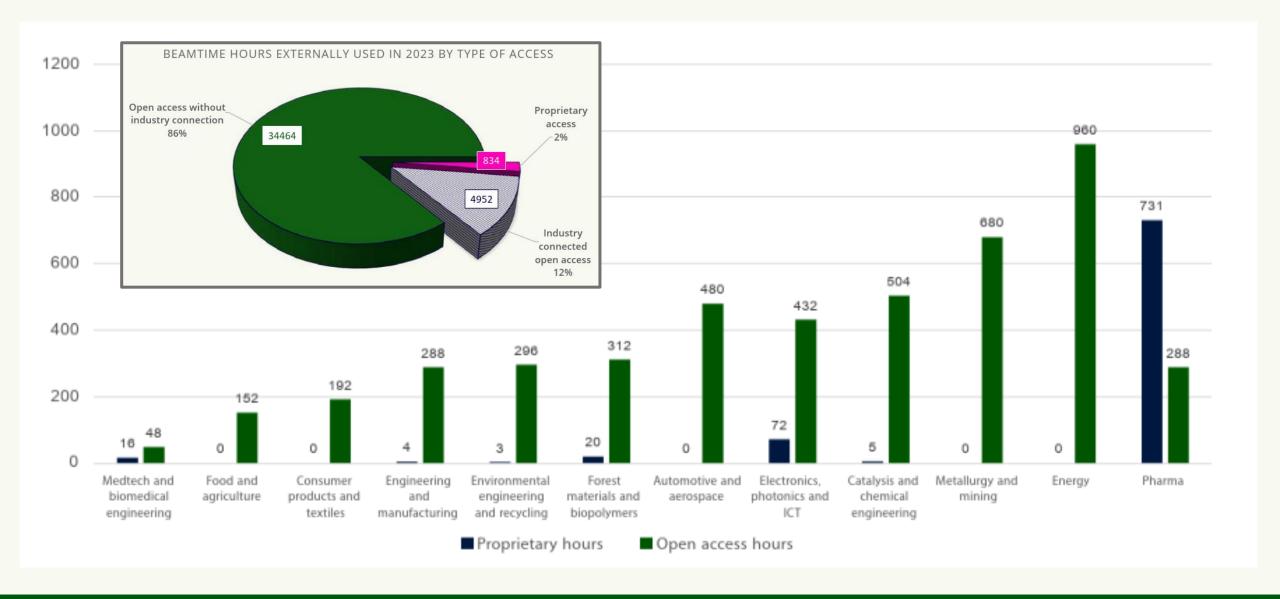
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### INDUSTRY-CONNECTED BEAMTIME HOURS IN 2023 BY TYPE OF ACCESS AND INDUSTRY SECTOR





### S S U E

### Value chain and functions for industry



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Problem description

Physical representation

Experimental environment

Measurement and data collection

Analysis of test data

Interpretation of results

Conclusions from the experiment

Infrastructure & availability

Capability & scaling

Data power & storage

Service level & quality

Knowledge & training

Collaboration & IP

### Identified barriers for industry













Access

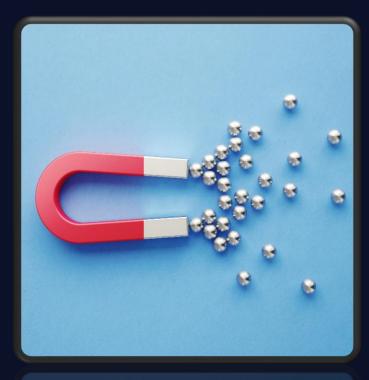
Packaging

Mandate

Dependencies







Join



Align



Execute

